

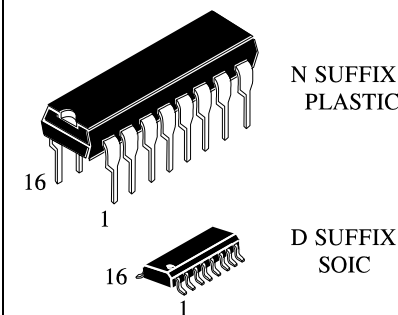
BCD-TO-DECIMAL DECODER HIGH-VOLTAGE SILICON-GATE CMOS

IW4028B

The IW4028B types are BCD-to-decimal or binary-to-octal decoders consisting of buffering on all 4 inputs, decoding-logic gates, and 10 output buffers. A BCD code applied to the four inputs, A0 to A3 results in a high level at the selected one of 10 decimal decoded outputs. Similarly, a 3-bit binary code applied to inputs A0 through A2 is decoded in octal code at output 0 to7 if A3="0". High drive capability is provided at all outputs to enhance dc and dynamic performance in high fan-out applications.

FEATURES

- BCD-to-decimal decoding or binary-to-octal decoding
- Operating Voltage Range: 3.0 to 18 V
- Maximum input current of 1 μ A at 18 V over full package-temperature range; 100 nA at 18 V and 25°C
- Noise margin (over full package temperature range):
 - 1.0 V min @ 5.0 V supply
 - 2.0 V min @ 10.0 V supply
 - 2.5 V min @ 15.0 V supply

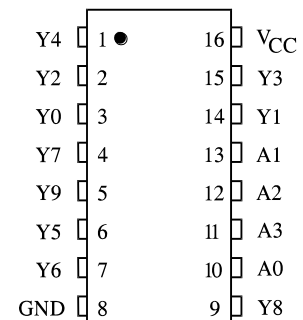


ORDERING INFORMATION
 IW4028BN Plastic
 IW4028BD SOIC
 T_A = -55° to 125° C for all packages

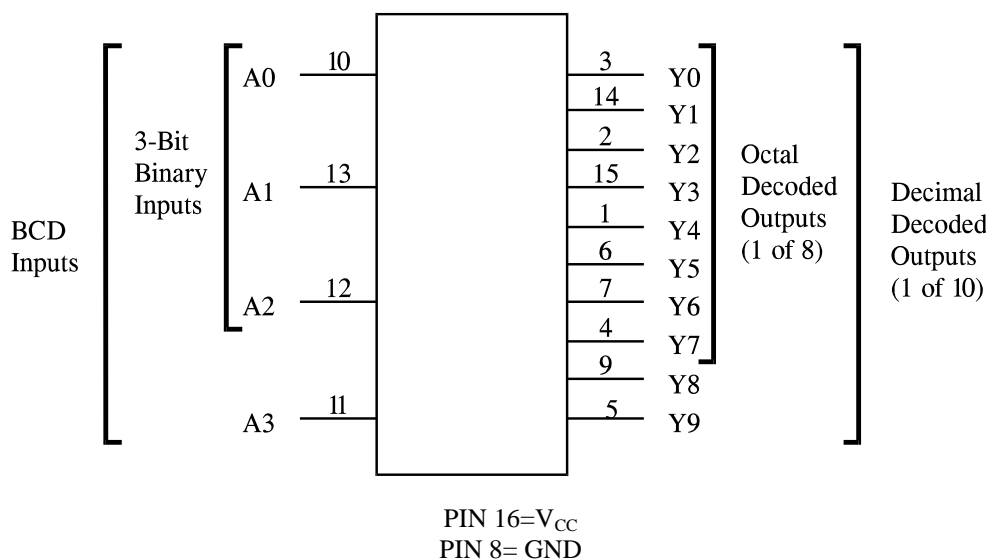
ORDERING INFORMATION

Device	Operating Temperature Range	Package	Packing
IW4028BN	T _A = - 55 ... + 125 °C	DIP 16	Tube
IW4028BD		SOP16	Tube
IW4028BDT		SOP16	Tape & Reel

PIN ASSIGNMENT



LOGIC DIAGRAM



MAXIMUM RATINGS*

Symbol	Parameter	Value	Unit
V _{CC}	DC Supply Voltage (Referenced to GND)	-0.5 to +20	V
V _{IN}	DC Input Voltage (Referenced to GND)	-0.5 to V _{CC} +0.5	V
V _{OUT}	DC Output Voltage (Referenced to GND)	-0.5 to V _{CC} +0.5	V
I _{IN}	DC Input Current, per Pin	±10	mA
P _D	Power Dissipation in Still Air, Plastic DIP+ SOIC Package+	750 500	mW
P _D	Power Dissipation per Output Transistor	100	mW
T _{stg}	Storage Temperature	-65 to +150	°C
T _L	Lead Temperature, 1 mm from Case for 10 Seconds (Plastic DIP or SOIC Package)	260	°C

* Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

+ Derating - Plastic DIP: - 10 mW/°C from 65° to 125°C
SOIC Package: - 7 mW/°C from 65° to 125°C

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V _{CC}	DC Supply Voltage (Referenced to GND)	3.0	18	V
V _{IN} , V _{OUT}	DC Input Voltage, Output Voltage (Referenced to GND)	0	V _{CC}	V
T _A	Operating Temperature, All Package Types	-55	+125	°C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation, V_{IN} and V_{OUT} should be constrained to the range $GND \leq (V_{IN} \text{ or } V_{OUT}) \leq V_{CC}$.

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or V_{CC}). Unused outputs must be left open.

DC ELECTRICAL CHARACTERISTICS (Voltages Referenced to GND)

Symbol	Parameter	Test Conditions	V _{CC} V	Guaranteed Limit			Unit
				≥-55°C	25°C	≤125°C	
V _{IH}	Minimum High-Level Input Voltage	V _{OUT} = 0.5 V or V _{CC} - 0.5V V _{OUT} = 1.0 V or V _{CC} - 1.0 V V _{OUT} = 1.5 V or V _{CC} - 1.5V	5.0	3.5	3.5	3.5	V
			10	7	7	7	
			15	11	11	11	
V _{IL}	Maximum Low -Level Input Voltage	V _{OUT} = 0.5 V or V _{CC} - 0.5V V _{OUT} = 1.0 V or V _{CC} - 1.0 V V _{OUT} = 1.5 V or V _{CC} - 1.5V	5.0	1.5	1.5	1.5	V
			10	3	3	3	
			15	4	4	4	
V _{OH}	Minimum High-Level Output Voltage	V _{IN} =GND or V _{CC}	5.0	4.95	4.95	4.95	V
			10	9.95	9.95	9.95	
			15	14.95	14.95	14.95	
V _{OL}	Maximum Low-Level Output Voltage	V _{IN} =GND or V _{CC}	5.0	0.05	0.05	0.05	V
			10	0.05	0.05	0.05	
			15	0.05	0.05	0.05	
I _{IN}	Maximum Input Leakage Current	V _{IN} = GND or V _{CC}	18	±0.1	±0.1	±1.0	μA
I _{CC}	Maximum Quiescent Supply Current (per Package)	V _{IN} = GND or V _{CC}	5.0	5	5	150	μA
			10	10	10	300	
			15	20	20	600	
			20	100	100	3000	
I _{OL}	Minimum Output Low (Sink) Current	V _{IN} = GND or V _{CC} V _{OL} =0.4 V V _{OL} =0.5 V V _{OL} =1.5 V	5.0	0.64	0.51	0.36	mA
			10	1.6	1.3	0.9	
			15	4.2	3.4	2.4	
I _{OH}	Minimum Output High (Source) Current	V _{IN} = GND or V _{CC} V _{OH} =2.5 V V _{OH} =4.6 V V _{OH} =9.5 V V _{OH} =13.5 V	5.0	-2	-1.6	-1.15	mA
			5.0	-0.64	-0.51	-0.36	
			10	-1.6	-1.3	-0.9	
			15	-4.2	-3.4	-2.4	

AC ELECTRICAL CHARACTERISTICS ($C_L=50\text{pF}$, $R_L=200\text{k}\Omega$, Input $t_r = t_f = 20\text{ ns}$)

Symbol	Parameter	V _{CC} V	Guaranteed Limit			Unit
			≥-55°C	25°C	≤125°C	
t _{PHL} , t _{PLH}	Maximum Propagation Delay, Input A to Output Y (Figure 1)	5.0	350	350	700	ns
		10	160	160	320	
		15	120	120	240	
t _{THL} , t _{TLH}	Maximum Output Transition Time, Any Output (Figure 1)	5.0	200	200	400	ns
		10	100	100	200	
		15	80	80	160	
C _{IN}	Maximum Input Capacitance	-		7.5		pF

FUNCTION TABLE

Inputs				Outputs									
A3	A2	A1	A0	Y0	Y1	Y2	Y3	Y4	Y5	Y6	Y7	Y8	Y9
L	L	L	L	H	L	L	L	L	L	L	L	L	L
L	L	L	H	L	H	L	L	L	L	L	L	L	L
L	L	H	L	L	L	H	L	L	L	L	L	L	L
L	L	H	H	L	L	L	H	L	L	L	L	L	L
L	H	L	L	L	L	L	L	H	L	L	L	L	L
L	H	L	H	L	L	L	L	L	H	L	L	L	L
L	H	H	L	L	L	L	L	L	L	H	L	L	L
L	H	H	H	L	L	L	L	L	L	L	H	L	L
H	L	L	L	L	L	L	L	L	L	L	L	H	L
H	L	L	H	L	L	L	L	L	L	L	L	L	H
H	L	H	L	L	L	L	L	L	L	L	L	L	L
H	L	H	H	L	L	L	L	L	L	L	L	L	L
H	H	L	L	L	L	L	L	L	L	L	L	L	L
H	H	L	H	L	L	L	L	L	L	L	L	L	L
H	H	H	L	L	L	L	L	L	L	L	L	L	L
H	H	H	H	L	L	L	L	L	L	L	L	L	L

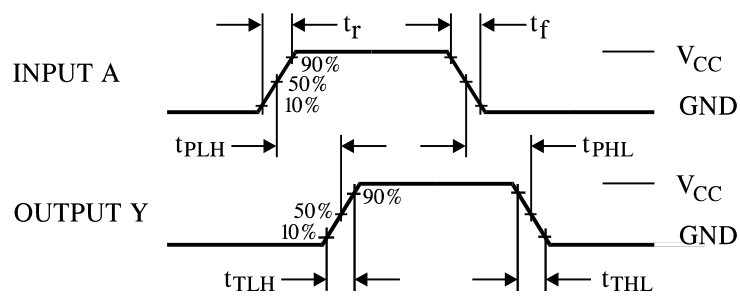


Figure 1. Switching Waveforms

EXPANDED LOGIC DIAGRAM

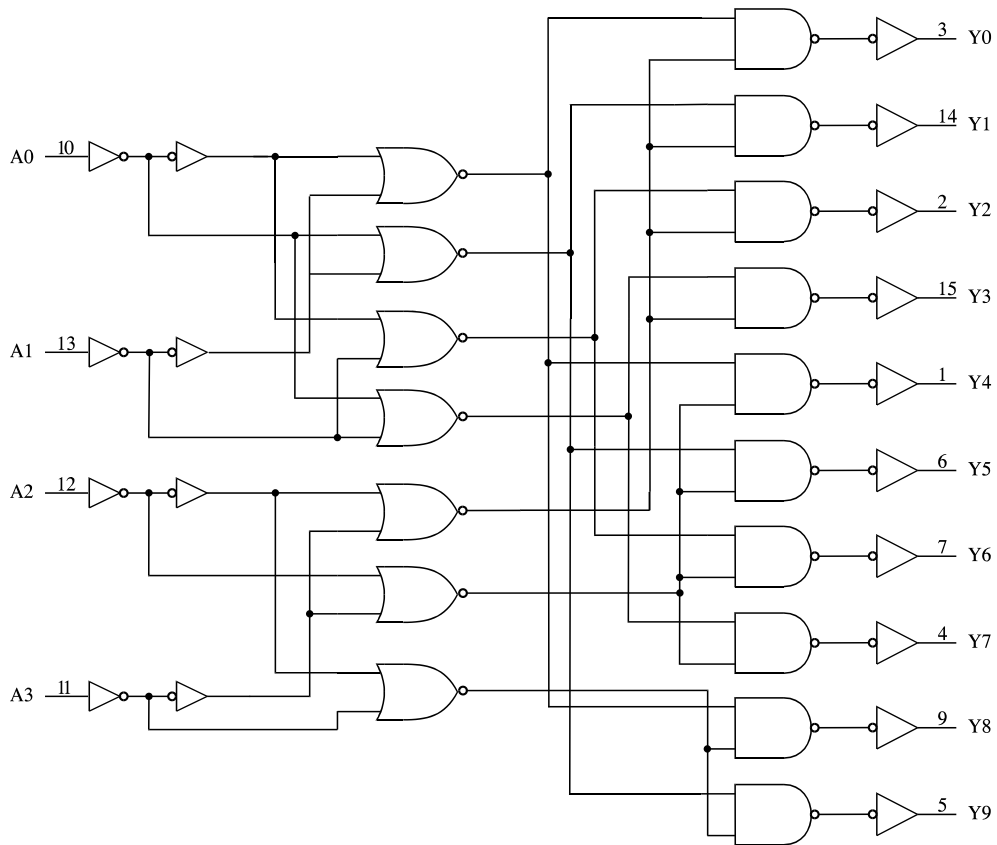
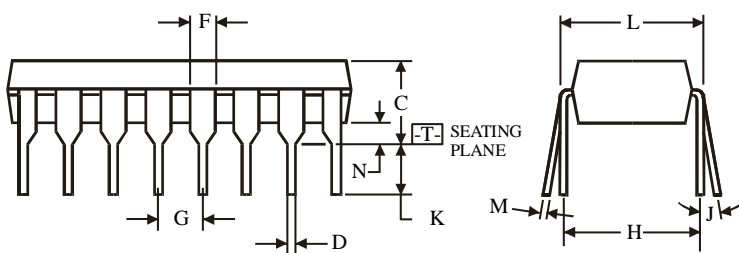
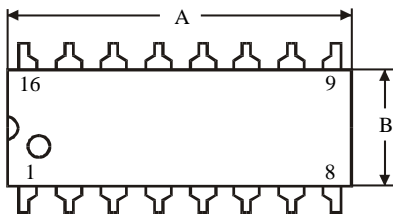
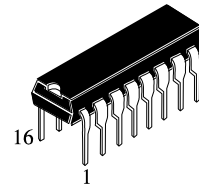


Figure 2.

PACKAGE DIMENSION

N SUFFIX PLASTIC
(MS - 001BB)



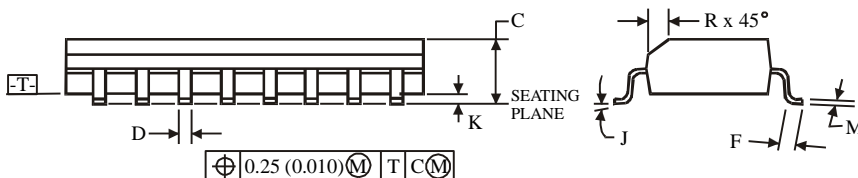
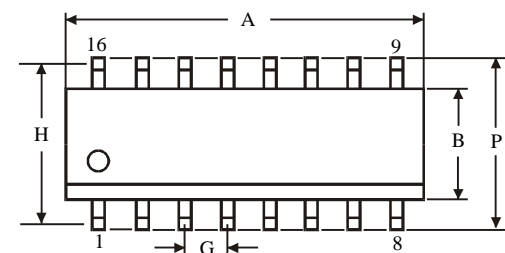
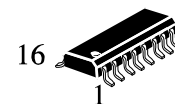
$\oplus 0.25 (0.010) \text{ (M) T}$

Symbol	Dimensions, mm	
	MIN	MAX
A	18.67	19.69
B	6.10	7.11
C		5.33
D	0.36	0.56
F	1.14	1.78
G	2.54	
H	7.62	
J	0°	10°
K	2.92	3.81
L	7.62	8.26
M	0.20	0.36
N	0.38	

NOTES:

- Dimensions "A", "B" do not include mold flash or protrusions. Maximum mold flash or protrusions 0.25 mm (0.010) per side.

D SUFFIX SOIC
(MS - 012AC)



$\oplus 0.25 (0.010) \text{ (M) T C (M)}$

Symbol.	Dimensions, mm	
	MIN	MAX
A	9.80	10.0
B	3.80	4.00
C	1.35	1.75
D	0.33	0.51
F	0.40	1.27
G	1.27	
H	5.72	
J	0°	8°
K	0.10	0.25
M	0.19	0.25
P	5.80	6.20
R	0.25	0.50

NOTES:

- Dimensions A and B do not include mold flash or protrusion.
- Maximum mold flash or protrusion 0.15 mm (0.006) per side for A, for B - 0.25 mm (0.010) per side.